

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A wafer holder for semiconductor manufacturing equipment, the wafer holder having a wafer-carrying surface and characterized in that the diameter ***a*** of the wafer holder wafer-carrying surface is not greater than the diameter ***b*** of the wafer holder surface on its side opposite the wafer-carrying surface, wherein the diameter ***b*** minus the diameter ***a*** is greater than $0\ \mu\text{m}$ and less than or equal to 35 mm.

Claim 2 (currently amended): The wafer holder set forth in claim 1, wherein the diameter ***b*** ~~is larger than~~ minus the diameter ***a*** ~~by 50 μm or more~~ is in the range from 50 μm to 35 mm.

Claim 3 (original): The wafer holder set forth in claim 1, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.

Claim 4 (original): The wafer holder set forth in claim 2, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.

Claim 5 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 1 is installed.

Claim 6 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 2 is installed.

Claim 7 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 3 is installed.

Claim 8 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 4 is installed.

Claim 9 (new): The wafer holder set forth in claim 1, wherein the diameter ***b*** minus the diameter ***a*** is greater than 10 mm and less than 30 mm.

Claim 10 (new): The wafer holder set forth in claim 1, wherein the diameter ***b*** is within the range from 100.02 to 110% of the diameter ***a***.

Claim 11 (new): The wafer holder set forth in claim 1, wherein the diameter ***b*** is within the range from 100.3 to 110% of the diameter ***a***.

Claim 12 (new): The wafer holder set forth in claim 1, wherein the diameter ***b*** is within the range from 103 to 109% of the diameter ***a***.